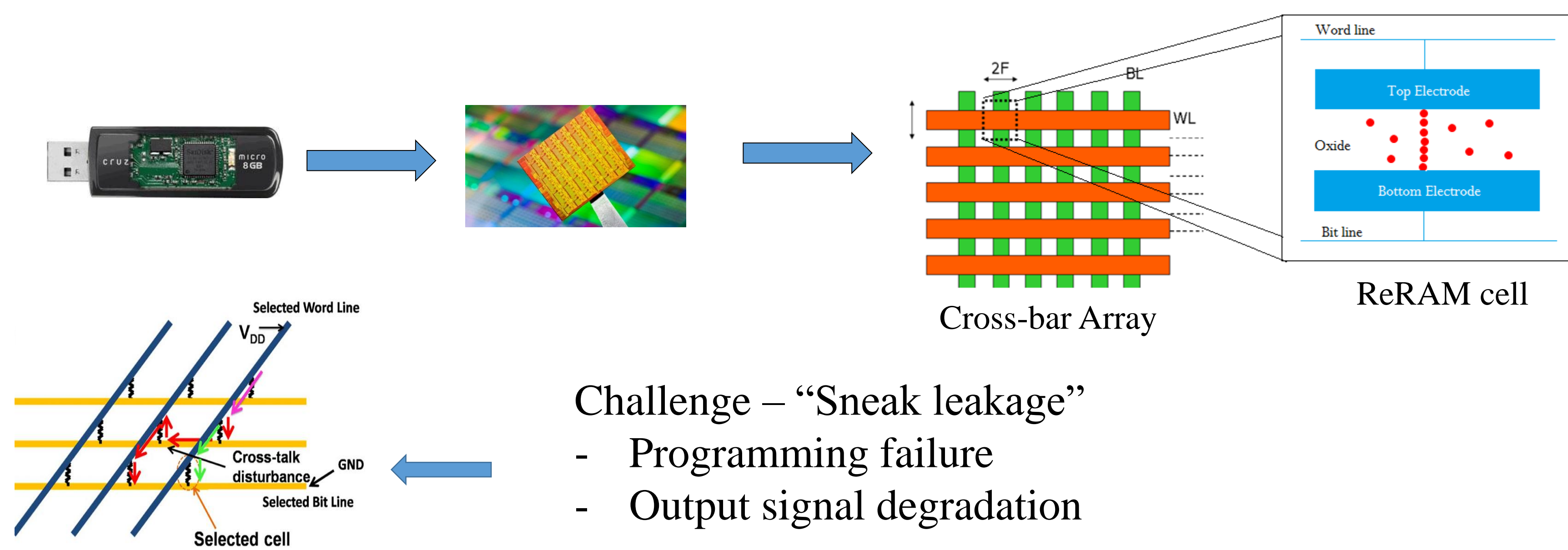


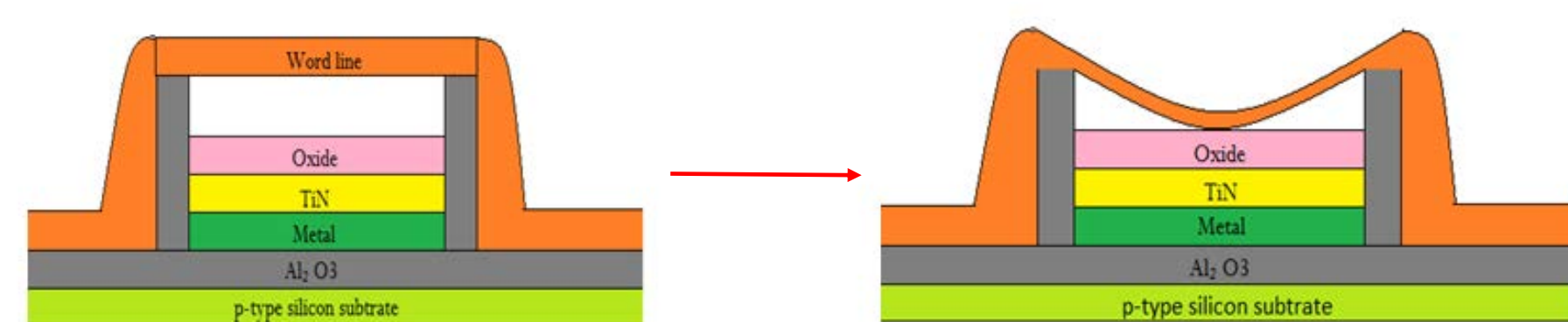
## Abstract

In recent years, ReRAM (Resistive Random Access Memory) has become one of the most promising nonvolatile memories. It is well-known for its high speed and low power consumption. However, ReRAM with high sneak-path leakage current is hindering the efficiency. A mechanical switch (MS) was proposed as a selector in a ReRAM cell to reduce the leakage current. Dimensions and materials of the beam were investigated to achieve the low pull-in and pull-out voltages. Tungsten, which has high melting point, was considered as a good material to be used in mechanical switch structure. In this project, many tests on MS were made to find the best dimension of word line beam (WL) to get both pull-in and pull-out voltages.

## ReRAM Structure and its Challenge



## Mechanical Switch Structure



$F_e = \frac{V^2 \epsilon A}{2g^2}$

$F_e$ : electrostatic force (N)  
V: voltage (V)  
A: area of the beam (m<sup>2</sup>)  
g: gap (m)  
 $\epsilon$ : permittivity

When a voltage is applied:  $F_e > F_s$

$F_s = k(g_0 - g)$

$F_s$ : restoring force (N)  
k: spring constant (N/m)  
 $g_0$  = initial gap (m)

$$V_{pull-in} = \sqrt{\frac{8kg_0^3}{27\epsilon A}}$$

**Material of the word line:**

Tungsten:

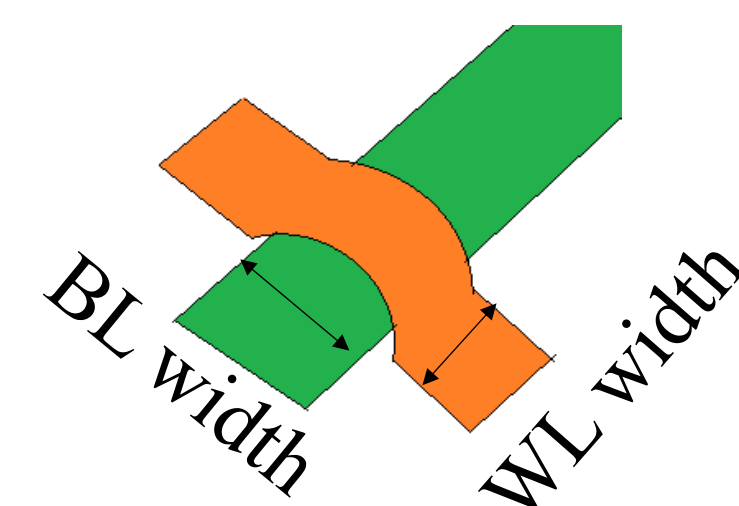
- High melting point
- High spring constant

**Gap:** 20nm

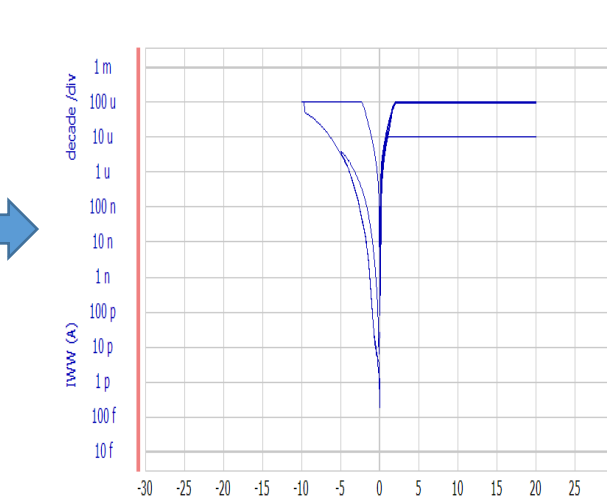
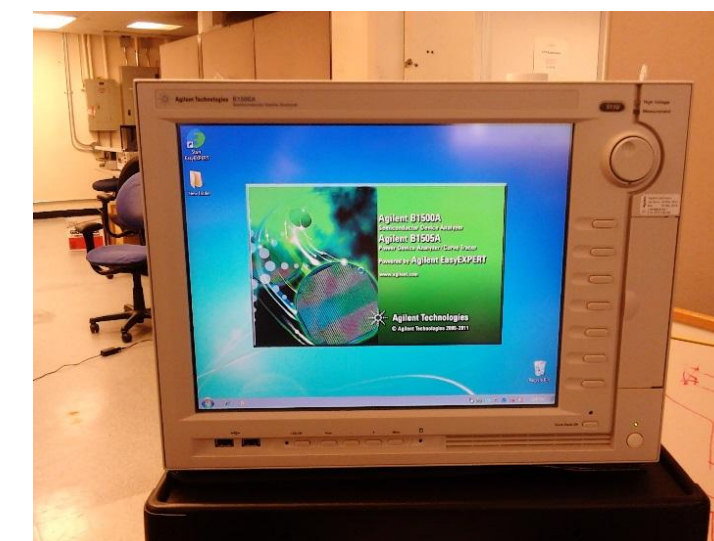
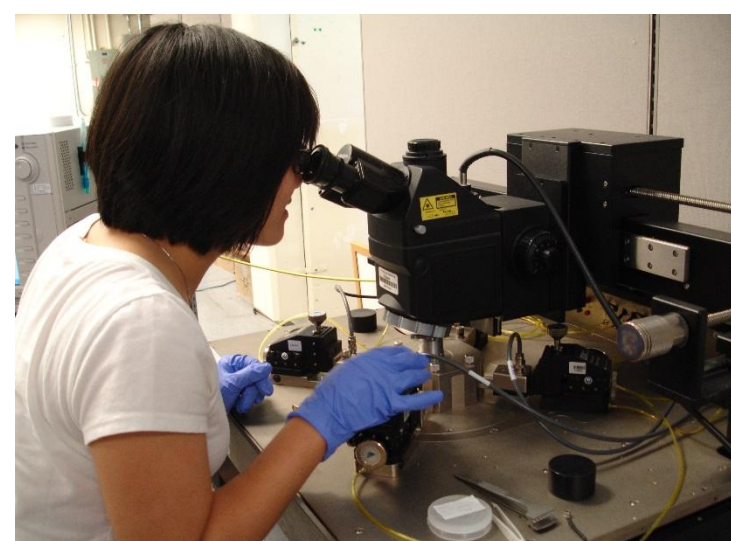
## Experimental method

Dimension:

Bit line width: 0.35  $\mu$ m - 4  $\mu$ m  
Word line width: 0.30  $\mu$ m - 8  $\mu$ m



Method:

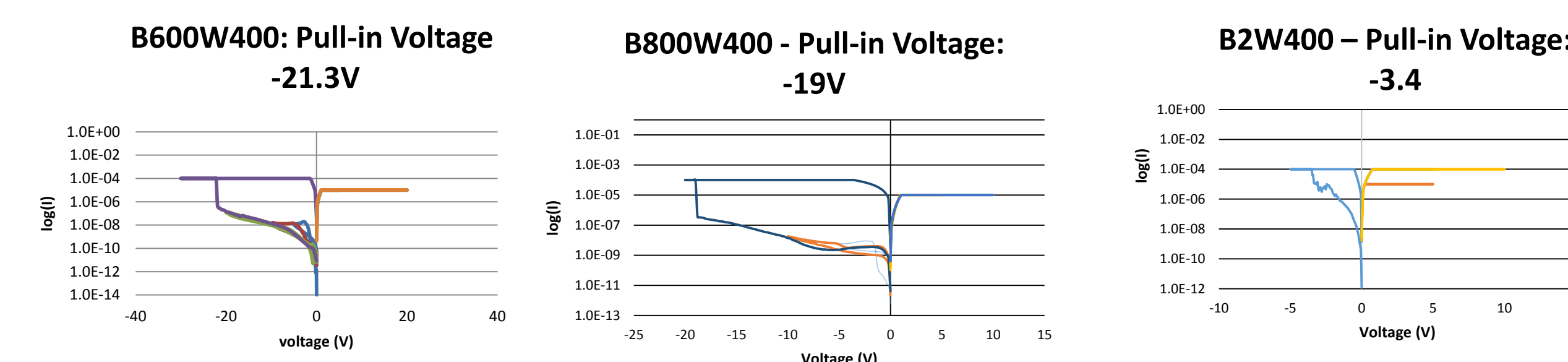


Cascade 4 Probe Station Semiconductor Device Analyzer

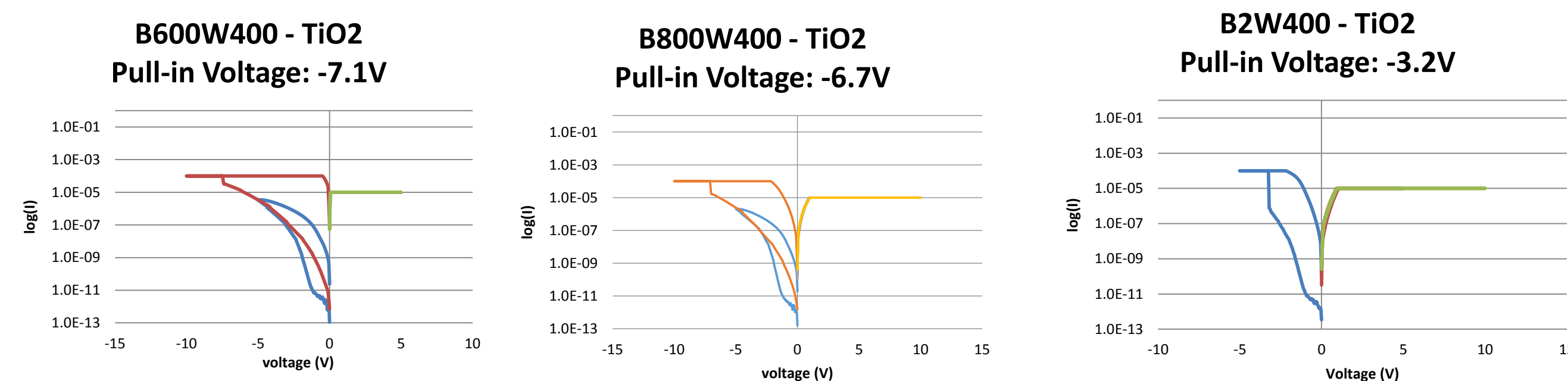
IV curve

## Results

Without TiO<sub>2</sub>



With TiO<sub>2</sub>



## Conclusion and Future Directions

- \* As increasing the bit line width (length of the beam), the pull-in voltage is smaller.
- \* Adding TiO<sub>2</sub> to surfaces of word line and bit line helps to reduce pull-in voltage.
- \* In the future, the thickness of the word line beam needs to be increased to get pull-out voltage.
- \* To reduce the pull-in voltage, the gap needs to be reduced.

## Acknowledgement

I would like to thank Prof. King Liu and Chuang Qian for all their help with guidance and support. This project was organized by Center for Energy Efficient Electronics (E<sup>3</sup>S) and funded by the National Science Foundation (NSF).

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## Support Information

This work was funded by National Science Foundation Award ECCS-0939514 & ECCS-1157089.

